

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Yaojian Lin</td><td>12/12/2008</td></tr><tr><td>Xusheng Bao</td><td>12/12/2008</td></tr><tr><td>Kang Chen</td><td>12/12/2008</td></tr><tr><td>Jianmin Fang</td><td>12/12/2008</td></tr></tbody></table>	Name	Execution Date	Yaojian Lin	12/12/2008	Xusheng Bao	12/12/2008	Kang Chen	12/12/2008	Jianmin Fang	12/12/2008	
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Yaojian Lin	12/12/2008										
Xusheng Bao	12/12/2008										
Kang Chen	12/12/2008										
Jianmin Fang	12/12/2008										
RECEIVING PARTY DATA											
Name:	STATS ChipPAC, Ltd.										
Street Address:	10 Ang Mo Kio Street 65										
Internal Address:	#05-17/20 Techpoint										
City:	Singapore										
State/Country:	SINGAPORE										
Postal Code:	569059										
PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12333977</td></tr></tbody></table>	Property Type	Number	Application Number:	12333977							
Property Type	Number										
Application Number:	12333977										
CORRESPONDENCE DATA											
Fax Number:	(602)264-2743										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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Address Line 4:	Tempe, ARIZONA 85284										
ATTORNEY DOCKET NUMBER:	2515.0151										
NAME OF SUBMITTER:	Robert D. Atkins										

CH \$40.00 12333977

500729589

PATENT
REEL: 021972 FRAME: 0863

Total Attachments: 4

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PATENT

REEL: 021972 FRAME: 0864

ASSIGNMENT AND AGREEMENT

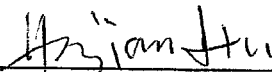
For good and valuable consideration, the receipt of which is hereby acknowledged, I, YAOJIAN LIN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING A VERTICAL INTERCONNECT STRUCTURE FOR 3-D FO-WLCSP, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0151, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the foreign, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the foreign to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the foreign to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

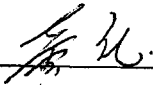


Signature for YAOJIAN LIN

Witnessed on this date:

12 Dec 2008

Signature of Witness:



Printed Name of Witness:

HUANG RUI

Address of Witness:

5 Yishun Street 23

Singapore 768822

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, XUSHENG BAO of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING A VERTICAL INTERCONNECT STRUCTURE FOR 3-D FO-WLCSP, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0151, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for XUSHENG BAO

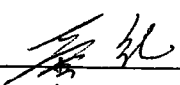
Witnessed on this date:

12 Dec 2008

Signature of Witness:

Printed Name of Witness:

Address of Witness:



HUANG RUI

5 Yishun Street 23

Singapore 768662

ASSIGNMENT AND AGREEMENT

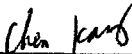
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Signature for KANG CHEN

Witnessed on this date: 12 Dec 2008

Signature of Witness: 

Printed Name of Witness: HUANG RUI

Address of Witness: 5 Yishun Street # 23

Singapore 768442

ASSIGNMENT AND AGREEMENT

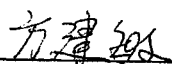
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Signature for JIANMIN FANG

Witnessed on this date: 12 Dec 2008

Signature of Witness: 

Printed Name of Witness: HUANG RUZ

Address of Witness: 5 Yishun Street 23
Singapore 768822.